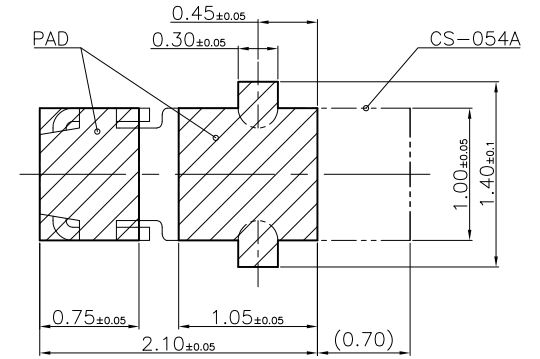
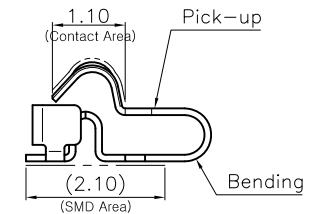
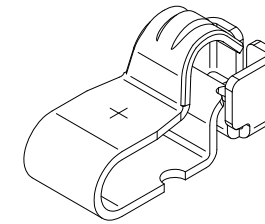
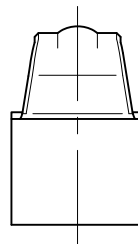
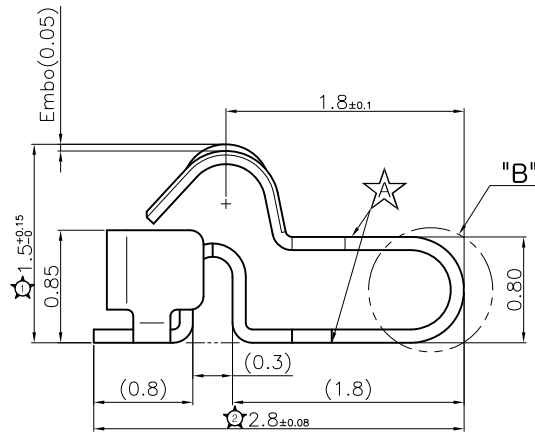


SIMULATION



RECOMMENDED PCB LAYOUT(Top View)



***NOTE**

1. PLATING
 - Contact Area : Au 0.1μm Min over Ni 1.5~4.0μm.
 - SMD Area : Au 0.05 μm Min over Ni 1.50~4.0μm.
 - Bending & Pick-up : Ni 1.5~3.5μm.
2. ☆ : C.T.Q
3. ☆ : 평탄도 0.05 Max.
4. Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~80% 범위 내
(0.36~0.48mm) => (1.02~1.14mm)
* CONTACT 가동거리(Max)는 0.6mm 이상으로 한다.
5. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.

1	Contact	Ti-Cu			Note.1			t0.1	
No	Part name	Material			Finish			Remarks	
General Tolerance		Scale	N/S	Units	mm	Sheet	TITLE	CS-054A Contact	
Dimension	mm (°)	Date	2014. 02. 04		1 of 1				
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved			
X.X	± 0.15								
X.XX	± 0.1								
X.XXX	± 0.05								
ANGLE	± 2°	 협진커넥터(주) HYUPJIN CONNECTOR, Co.,Ltd.					SW No.		Rev.
							DWG No.	CS-054A-A1	0